

IMAGE SENSOR PACKAGE

BACKGROUND OF THE INVENTION

Field of the Invention

The invention relates to an image sensor package, and more particularly to
5 an image sensor with increased product reliability and facilitated manufacturing processes.

Description of the Related Art

Referring to FIG. 1, which is a cross-sectional view showing an image
sensor package. The image sensor includes a plurality of lower metal sheets10
10 arranged in an array, each of the lower metal sheets10 having an upper surface26
and a lower surface28. A plurality of upper metal sheets12 arranged in an array,
each of the upper metal sheets12 having an upper surface38 and a lower surface40,
the lower surfaces40 of the upper metal sheets12 being stacked on the upper
surfaces26of the lower metal sheets10. An encapsulant14 is for encapsulating the
15 lower metal sheets10 and the upper metal sheets12. Wherein the upper surfaces38
of the upper metal sheets12 are exposed from the encapsulant14. The lower
surfaces28 of the lower metal sheets10 are exposed from the encapsulant14 and
electrically connected to the printed circuit board, and the encapsulant14 is
formed with a frame layer16 around the upper surfaces38 of the upper metal
20 sheets12 to define a chamber42 together with the upper metal sheets12. A
photosensitive chip18 arranged within the chamber. A plurality of wires20 are for

electrically connecting the photosensitive chip18 to the upper surfaces38 of the upper metal sheets12. A transparent layer22 arranged on the frame layer16 of the encapsulant14 to cover the photosensitive chip18.

5 The above-mentioned the patent has some advantages, but it has following drawbacks.

1.Since the wires 20 are electrically connected the chip18 to the upper surface38 of the upper metal sheets12 for transmitting signals from the chip18 to the lower metal sheets12. Thus, the upper metals12 and the lower metal sheets10 much be tight stacked.

10 SUMMARY OF THE INVENTION

An object of the invention is to provide an image sensor package with improved package reliability.

Still another object of the invention is to provide an image sensor package, wherein the wire bonding process may be easily performed and the product yield
15 may be increased.

To achieve the above-mentioned objects, the invention includes plural lower metal sheets, plural upper metal sheets stacked on the lower metal sheets, and an encapsulant for encapsulating the lower and upper metal sheets. The lower metal formed with a first hole, the upper metal sheets formed a second hole penetrated
20 from the upper surface to the lower surface. Wherein the encapsulant filled into the second hole and first hole to tighten the upper metal sheets and the lower

metal sheets. A photosensitive chip arranged within the chamber, plural wires for electrically connecting the chip to the upper surfaces of the lower metal sheets, and a transparent layer arranged on the frame layer to cover the chip.

BRIEF DESCRIPTION OF THE DRAWINGS

5 FIG. 1 is a cross-sectional view showing an image sensor package.

FIG. 2 is a cross-sectional view showing an image sensor package of the present invention.

FIG. 3 is a first schematic view showing an image sensor package of the invention.

10 FIG.4 is a second schematic view showing an image sensor package of the invention.

FIG.5 is a third schematic view showing an image sensor package of the invention.

DETAILED DESCRIPTION OF THE INVENTION

15 Referring to FIG. 2, an image sensor package of the invention includes a plurality of lower metal sheets 46 arranged in an array, a plurality of upper metal sheets 48 arranged in an array, an encapsulant 50, a frame layer 52, a photosensitive chip 54, a plurality of wires 56, and a transparent layer 58..

20 Please referring to FIG.3 and FIG.4, Each lower metal sheet 46 has an upper surface 60 and a lower surface 62, and formed with a first hole 64, which is

a cavity.

Each of the upper metal sheet48 has an upper surface68 and a lower surface70, and formed with a second hole 72 penetrated from the upper surface68 to the lower surface70. The lower surfaces70 of the upper metal sheets48 are
5 stacked on the upper surfaces60 of the lower metal sheets46, then the second hole72 corresponding with the first hole64.

The encapsulant54 is encapsulated the lower metal sheets 46and the upper metal sheets 48 via integrated mold, and filled into the first hole64 and the second hole 72to tighten the lower metal sheets46 and upper metal sheets48. Wherein the
10 upper surfaces60 of the lower metal sheets46 are exposed from the encapsulant54. The lower surfaces62 of the lower metal sheets46 are exposed from the encapsulant54 and electrically connected to the printed circuit board32 via solder30. The encapsulant54 is formed with a frame layer52 around the upper surfaces68 of the upper metal sheets48 to define a chamber74 together with the
15 upper metal sheets48.

The photosensitive chip 54 is arranged on the middle board 67 and located within the chamber 74.

The plurality of wires 56 are electrically connected the photosensitive chip 54 to the upper surfaces 60 of the upper metal sheets 46 so as to transfer signals
20 from the photosensitive chip 54 to the lower metal sheets 46.

The transparent layer 58 is a piece of transparent glass arranged on the

frame layer 52 of the encapsulant 50 to cover the photosensitive chip 54. Thus, the photosensitive chip 54 may receive optical signals passing through the transparent layer 58.

The invention has the following advantages.

- 5 1. Since the combination of the upper and lower metal sheets 48 and 46 is thicker, the solder 30 may climb to the upper metal sheets 48 from the lower metal sheets 46 during the SMT process for mounting the image sensor to the printed circuit board 32. Therefore, the package body can be mounted to the printed circuit board 32 with great stability.
- 10 2. Since the encapsulant 54 is filled into the first hole 64 and first hole 72, so as to the upper metal sheets 48 and lower metal sheets 46 may package tight.

While the invention has been described by way of examples and in terms of preferred embodiments, it is to be understood that the invention is not limited to
15 the disclosed embodiments. To the contrary, it is intended to cover various modifications. Therefore, the scope of the appended claims should be accorded the broadest interpretation so as to encompass all such modifications.